

1. CHARACTERISTICS

Transition Point (°C)	309
Deformation Point (°C)	327
Softening Point (°C)	350
Thermal Expansion Coefficient 40-250°C ($\times 10^{-6}/^{\circ}\text{C}$)	6.7
Specific Gravity (g/cc)	5.1
Dielectric Constant 1 MHz, 25°C	12.2
Volume Resistivity $\log_{10} (\Omega - \text{cm})$ at 250°C	9.4
Dielectric Loss Tangent 1 MHz, 25°C	0.0034
Acid Durability (mg/cm ²) 1N HCL 25°C 5 min.	0.9
18N H ₂ SO ₄ 50°C, 5 min.	0.4
Thermal Conductivity 25°C (Cal/cm. sec. °C)	0.0023
Alpha/Emission ($\alpha/\text{cm}^2/\text{hr.}$)	0.8

2. RECOMMENDED PRE-CLEANING

Steps	Solution	Temp.	Period
a. De-scaling	50% H ₂ SO ₄	75°C - 95°C	1 min.
b. Tap water rinse		25°C	2 min. min.
c. Acid washing	10% H ₂ SO ₄	25°C	10 sec.
d. Tap water rinse		25°C	2 min. min.
e. Distilled water rinse		25°C	2 min. min.
f. Tin plating			

3. RECOMMENDED TIN PLATING CONDITION
3.1 Plating Solution

— Sulphuric Acid Bath

105 cc/liter

30 gram/liter

40 cc/liter

H₂SO₄

SnSO₄

Tinglo Culmo Starter Conc.

— Temperature of Plating Bath 17-21°C

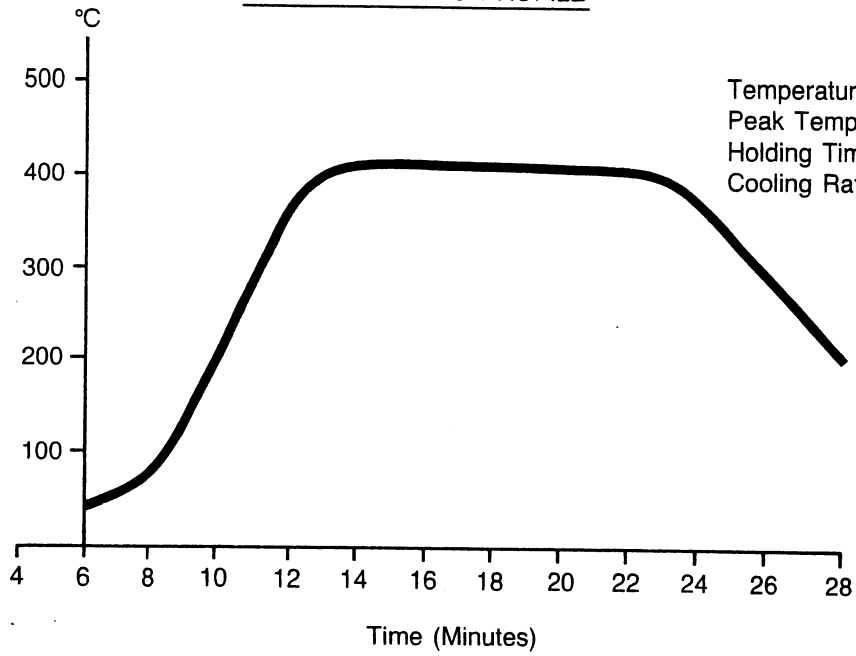
3.2 Current Density — 1.4-2.5 Ampere/SQ DM (Square Decimeter)

3.3 Plating Time 10 Minutes Max.



KC-402 DATA SHEET

TYPICAL SEALING PROFILE



Temperature Rise 40-110°C/Min
Peak Temperature 425-440°C
Holding Time at Peak 6-11 minutes
Cooling Rate 20-40°C/min.